



ECUS INTERNATIONAL CO., LTD

THT Power inductor Unshielded

Part Number: E10406TPR1016B

Product Identification

Product Series:

SMD Power Inductor Unshielded-----SPU Series

SMD Power Inductor Shielded-----SPS Series

SMD Power Inductor Low profile-----SPL Series

SMD Power Inductor High current-----SPH Series

SMD Power Inductor Flat wire-----SPF Series

SMD Power inductor Mag-Resin Shielded-----SPM Series

THT Power Radial Inductor-----TPR Series

Product Identification:

E1

(Type)

7335

(Size)

SPS

(Series)

1R5

(Inductance)

7

(Tolerance)

R

(Packing)

Type:

E1=ECUS Singl-Winding Products, E2=ECUS Dual-Winding Products

Size:

7335--Length: 7.3mm, Height: 3.5mm

0603--Length: 0.06inch/1.6mm, Width: 0.03inch/0.8mm

Series:

SPU Series, SPS Series, SPL Series, SPH Series

SPF Series, SPM Series, TPR Series

Inductance:

1N0 = 1nH, 10N = 10nH, R10 = 100nH = 0.1μH, 1R0 = 1000nH = 1μH

100 = 10μH, 101 = 100μH, 102 = 1000μH = 1mH, 103=10mH

Tolerance:

1-1%, 2-2%, 5-5%, 6-10%, 7-20%, 8-25%, 9-30%

Packing:

R-Tape and Reel, T-Tray, B-Bulk

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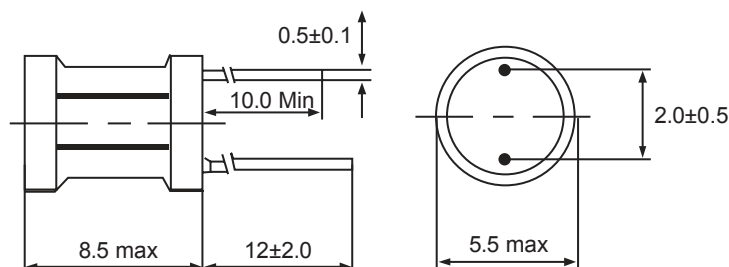
Features

- Radial through-hole inductor
- Small size
- With shrink tube
- Operating temperature: -40 °C to +125 °C
- RoHS compliant

Applications

- Signal filtering
- Power line in- and output filter
- Switches, switching power supply for small and medium voltage
- Power supply filter
- EMI filter

Mechanical Dimensions (in mm)



Electrical Characteristics

Property	Test Conditions	Value	Unit	Tol.
Inductance	1 KHz/0.3V	100	uH	±10%
RDC	@20°C	1.0	Ω	Max
IDC	ΔT=40°C	300	mA	Max

Test Equipments

VJ 4997D for L

HP4338B for RDC

VJ 4997DIVJ 3994C for IFE



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Delivery mode and packing unit

- Bulk
- Packing unit: 500 pcs

Notes

Electrical Specifications @ 25 °C (Values specified at 25 °C)

RoHS Directive 2002/95/EC Jan 27, 2003 including Annex.

Customers should verify actual device performance in their specific applications

Soldering Profiles

Figure 1 Classification Profile (Not to scale)

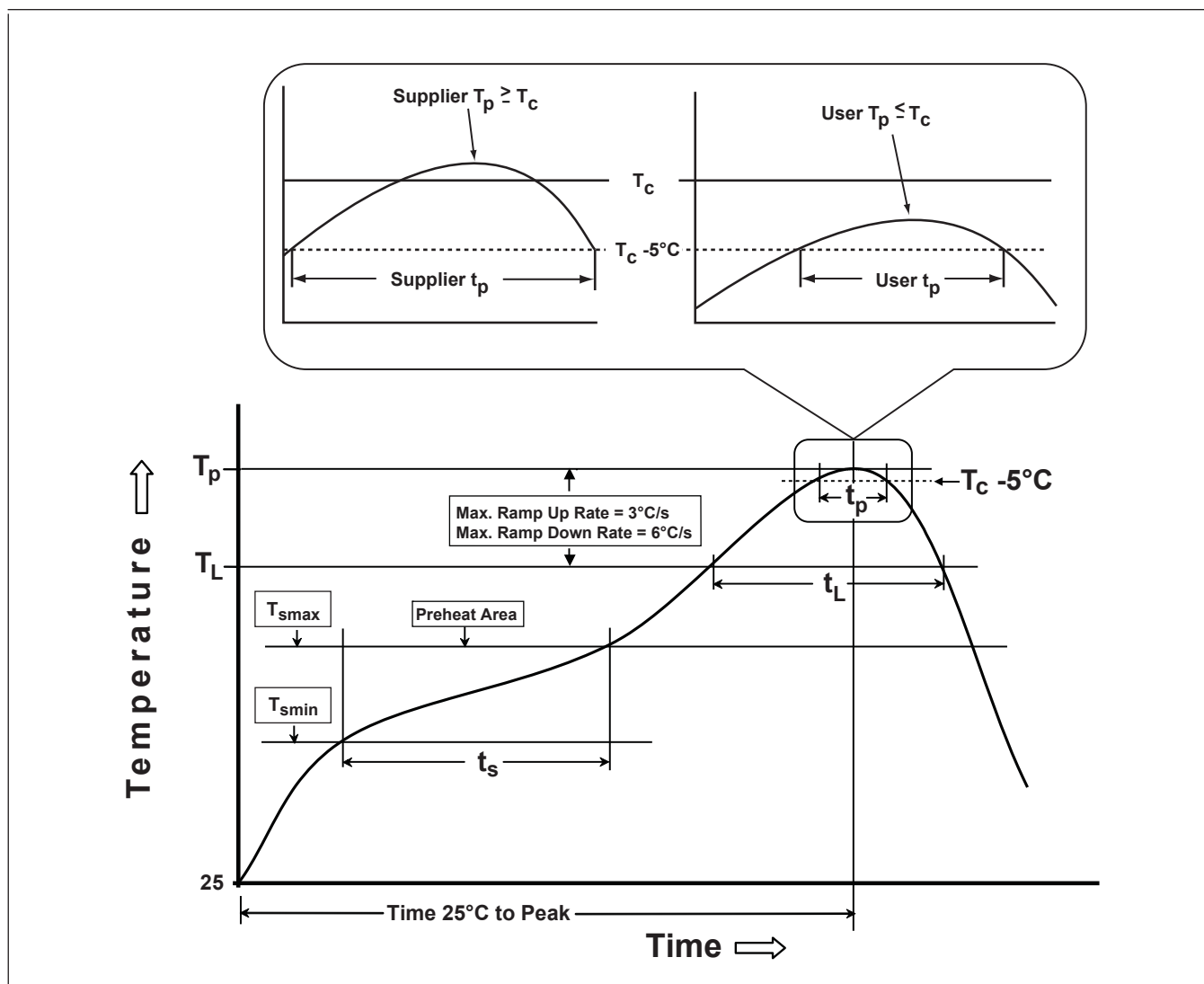


Table 1 SnPb Eutectic Process - Classification Temperatures (T_c)

Package Thickness	Volume mm^3 <350	Volume mm^3 ≥ 350
<2.5 mm	235 °C	220 °C
≥ 2.5 mm	220 °C	220 °C

Table 2 Pb-Free Process - Classification Temperatures (T_c)

Package Thickness	Volume mm^3 <350	Volume mm^3 350 - 2000	Volume mm^3 >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm - 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

Soldering Profiles

Table 3 Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat/Soak		
Temperature Min (T_{smin})	100 °C	150 °C
Temperature Max (T_{smax})	150 °C	200 °C
Time (t_s) from (T_{smin} to T_{smax})	60-120 seconds	60-120 seconds
Ramp-up rate (T_L to T_p)	3 °C/second max.	3 °C/second max.
Liquidous temperature (T_L)	183 °C	217 °C
Time (t_L) maintained above T_L	60-150 seconds	60-150 seconds
Peak package body temperature (T_p)	For users T_p must not exceed the Classification temp in Table 1. For suppliers T_p must equal or exceed the Classification temp in Table 1.	For users T_p must not exceed the Classification temp in Table 2 For suppliers T_p must equal or exceed the Classification temp in Table 2.
Time (t_p)* within 5 °C of the specified classification temperature (T_c), see Figure 1.	20* seconds	30* seconds
Ramp-down rate (T_p to T_L)	6 °C/second max.	6 °C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.
* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.		

Note 1: All temperatures refer to the center of the package, measured on the package body surface that is facing up during assembly reflow (e.g., live-bug). If parts are reflowed in other than the normal live-bug assembly reflow orientation (i.e., dead-bug), T_p **shall** be within ± 2 °C of the live-bug T_p and still meet the T_c requirements, otherwise, the profile **shall** be adjusted to achieve the latter. To accurately measure actual peak package body temperatures refer to JEP140 for recommended thermocouple use.

Note 2: Reflow profiles in this document are for classification/preconditioning and are not meant to specify board assembly profiles. Actual board assembly profiles should be developed based on specific process needs and board designs and should not exceed the parameters in Table 3.

For example, if T_c is 260 °C and time t_p is 30 seconds, this means the following for the supplier and the user.

For a supplier: The peak temperature must be at least 260 °C. The time above 255 °C must be at least 30 seconds.

For a user: The peak temperature must not exceed 260 °C. The time above 255 °C must not exceed 30 seconds.

Note 3: All components in the test load **shall** meet the classification profile requirements.

Note 4: SMD packages classified to a given moisture sensitivity level by using Procedures or Criteria defined within any previous version of J-STD-020, JESD22-A112 (rescinded), IPC-SM-786 (rescinded) do not need to be reclassified to the current revision unless a change in classification level or a higher peak classification temperature is desired.

Cautions and Warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.
- Specifications are subject to change without notice.
- Customers should verify actual device performance in their specific applications

Important Notes

The following applies to all products named in this publication:

1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application.
As a rule, ECUS is either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an ECUS product with the properties described in the product specification is suitable for use in a particular customer application.
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